

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1. (currently amended): A semiconductor device, comprising:

a semiconductor element with an area for a main surface of 1 mm² or greater;

a substrate having a thermal conductivity of 170 W/m-K or greater and having an upper surface on which said element is mounted and a bottom surface which is positioned on the opposite side;

a ratio H/L being 0.3 or greater, with L being the length in the long direction of a main surface of said semiconductor element, and H being the distance from a semiconductor element mounting part on said upper surface of said substrate to said bottom surface.

Claim 2. (original): A semiconductor device as described in Claim 1, wherein:

said semiconductor element is a light emitting element;

a part of said substrate on which said element is mounted is formed as a cavity;

and a metal layer is formed on said upper surface.

Claim 3. (original): A semiconductor device as described in Claim 2, wherein:

there is a connection member which connects between said substrate and a terminal plate which supplies power to said semiconductor light emitting element;

said connection member is placed at a position separate from said cavity;

a means for preventing infiltration of said connection member into said cavity is provided on said upper surface adjacent to said connection member.